

**AMENDMENTS TO THE CLAIMS**

Please **AMEND** claims 1, 5 and 13 as shown below.

Please **CANCEL** claims 14-20 without prejudice or disclaimer.

The following is a complete list of all claims in this application.

1. (Currently amended) An LCD, comprising:

a substrate;

a pixel array formed on a display region of the substrate in a matrix configuration;

a plurality of first terminals formed at a non-display region of the substrate, the first terminals having a contact region and applying an electrical signal to a plurality of column lines and row lines of the pixel array;

a protective layer having contact holes formed corresponding to the contact region of each of the first terminals, and covering the pixel array and the first terminals; and

a plurality of first pads formed on the protective layer overlapping each of the first terminals,

wherein the first pads include a first contact region contacting the first terminals and a second contact region defined as a region of the first pads except the first contact region,

wherein the second contact region is substantially larger than the first contact region.

~~wherein the first pads are electrically connected through the contact holes to each of the first terminals, and the first pads have a surface area substantially larger than that of the contact holes.~~

2. (Original) The LCD of claim 1, wherein the protective layer has 5  $\mu\text{m}$  or more thick.

3. (Original) The LCD of claim 1, wherein the first terminals are aligned in a zigzag

fashion of two rows.

4. (Original) The LCD of claim 3, wherein each of first inner terminals arranged along an inside portion of a first row among the first terminals, has a first contact region at an inner portion thereof and each of first outer terminals arranged along an outside portion of a second row among the first terminals has a second contact region at an outer portion thereof.

5. (Currently amended) The LCD of claim 4, further comprising at least one or more IC device output terminals of which are bonded to the second contact region ~~other than the contact region~~ of the first pads by a bump bonding method.

6. (Original) The LCD of claim 5, further comprising a plurality of second pads which are formed on the protective layer to be aligned along an edge portion of the substrate in one row, and wherein input terminals of the IC device are respectively bonded to one side of each second pad.

7. (Original) The LCD of claim 6, wherein the other side of each second pad is bonded to terminals of a flexible printed circuit board.

8. (Original) The LCD of claim 6, wherein the plurality of second pads are respectively compiled through at least one or more contact hole to a plurality of second terminals that are formed at a lower portion of the protective layer.

9. (Original) The LCD of claim 8, wherein an entire surface area of at least one or more contact region of each second terminal is no more than one third of an entire surface area of each terminal.

10. (Original) The LCD of claim 9, wherein the second terminals respectively have the contact regions that are arranged at both ends of the second terminals in a longitudinal direction.

11. (Original) The LCD of claim 9, wherein the second terminals respectively have the plurality of contact regions that are arranged at regular intervals in the longitudinal direction.

12. (Original) The LCD of claim 9, wherein the second terminals respectively have an elongated contact regions that are arranged at both ends of the second terminals in a lateral direction.

13. (Currently amended) The LCD of claim 1, wherein the first pads are aligned in one row, and connected through ~~an area except~~ the second contact region to terminals of a TCP, a COF or an FPC.

14-20. (Cancelled)